

In the claims:

1. (Currently Amended) A semiconductor processing chamber comprising:
 - a vacuum chamber body having an open upper end;
 - a hinge coupled to the chamber body and having a shaft disposed in a fixed position relative to the chamber body;
 - a lid assembly coupled to the chamber body by the hinge, the lid assembly rotatable about the shaft of the hinge between a first position sealing the open upper end and a second position clear of the upper end, the lid assembly comprising a PVD target; and
 - a motor coupled to the hinge for moving the lid assembly between at least the first position and the second position, wherein the hinge further comprises:
 - one or more mounting brackets coupled to the lid assembly;
 - the shaft coupled to the mounting brackets, wherein the shaft is coplanar with an upper surface of the chamber body; and
 - one or more bearing mounts rotatably coupled to the shaft.
2. (Cancelled)
3. (Currently Amended) The semiconductor processing chamber of ~~claim 2~~ claim 1, wherein the motor is coupled to the shaft.
4. (Cancelled)
5. (Currently Amended) The semiconductor processing chamber of ~~claim 2~~ claim 1, wherein the bearing mounts are coupled to the chamber body, a frame circumscribing the chamber body or a processing platform having the chamber body coupled thereto.
6. (Previously Presented) The semiconductor processing chamber of claim 1, wherein the lid assembly further comprises a magnetron.

7. (Previously Presented) The semiconductor processing chamber of claim 1 further comprising:

a plurality of first locating devices disposed between the lid assembly and the chamber body disposed proximate the shaft of the hinge; and

a plurality of second locating devices disposed between the lid assembly and the chamber body, the second locating devices disposed outward of the first locating devices relative the shaft.

8. (Original) The semiconductor processing chamber of claim 7, wherein each of the first locating devices further comprises:

a pin and a bushing having a "C" shaped cross section.

9. (Original) The semiconductor processing chamber of claim 8, wherein each of the second locating devices further comprises:

a pin and a cylindrical bushing.

10. (Original) The semiconductor processing chamber of claim 8, wherein the pin is coupled to the lid assembly.

11. (Currently Amended) A semiconductor processing chamber comprising:

a chamber body having sidewalls and a bottom defining an interior volume;

a lid coupled to the chamber body and having a bottom movable between a first position enclosing the interior volume and a second position;

a target coupled to the bottom of the lid;

a first mounting bracket coupled to the lid assembly;

one or more bearing mounts coupled to the chamber body;

a shaft having a fixed position relative to the chamber body and lid assembly, the shaft coupled to the first mounting bracket and rotatably disposed through the bearing mounts, wherein the shaft is coplanar with an upper surface of the chamber body; and

a motor coupled to at least one of the shaft or first mounting bracket for moving the lid assembly between at least the first position and the second position.

12. (Original) The semiconductor processing chamber of claim 11 further comprising:
a first bushing having a "C" shaped cross section disposed in the chamber body;
and

a first pin disposed between the lid assembly and the chamber body wherein a portion of the first pin mates with the first bushing.

13. (Original) The semiconductor processing chamber of claim 11 further comprising:
a first bushing having a "C" shaped cross section disposed in the chamber body;
a first pin disposed between the lid assembly and the chamber body wherein a portion of the first pin mates with the first bushing;

a second bushing having a cylindrical cross section disposed in the chamber body outward of the first bushing relative to the shaft; and

a second pin disposed between the lid assembly and the chamber body wherein a portion of the second pin mates with the second bushing.

14. (Cancelled)

15. (Original) The semiconductor processing chamber of claim 11, further comprising:

a second mounting bracket coupled to the lid assembly and the shaft; and

a brace coupled between the first and second mounting brackets.

16-18. (Cancelled)